



Application No. 09/748,708

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| In re the application of |) | |
| SALDANA et al. |) | Atty. Docket No. LAM2P222A |
| Application No. 09/748,708 |) | |
| Filed: December 22, 2000 |) | Examiner: Unassigned |
| For: POLISHING APPARATUS AND METHODS |) | |
| HAVING HIGH PROCESSING WORKLOAD |) | Group Art Unit: 3723 |
| FOR CONTROLLING POLISHING PRESSURE |) | |
| APPLIED BY POLISHING HEAD |) | Date: May 2, 2001 |

MARKED UP AMENDMENT

Please replace the paragraph that begins on page 1, line 9 with the following

This Application claims 35 U.S.C. § 120 priority based on, and is a continuation-in-part (CIP) of: (1) co-pending U.S. Patent Application No. [09/664,135] 09/644,135, filed August 22, 2000, entitled "SUBAPERTURE CHEMICAL MECHANICAL POLISHING SYSTEM," by Miguel A. Saldana, John M. Boyd, Yehiel Gotkis, and Aleksander A. Owczarz (the First Parent Application); and (2) co-pending U.S. Patent Application No. 09/668,667, filed September 22, 2000, entitled "APPARATUS AND METHODS FOR CONTROLLING RETAINING RING AND WAFER HEAD TILT FOR CHEMICAL MECHANICAL POLISHING," by Damon Vincent Williams (the Second Parent Application), each U.S. Patent Application is hereby incorporated by reference. Additionally, this Application is also related to co-pending U.S. Patent Application No. 09/493,978, filed January 28, 2000, entitled "SYSTEM METHOD FOR CONTROLLED POLISHING AND PLANARIZATION OF SEMICONDUCTOR WAFERS," by Rod Kistler and Yehiel Gotkis, and such related application is hereby incorporated by reference.--

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